

L Number	Hits	Search Text	DB	Time stamp
-	648	(216/24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:21
-	358	((216/24).CCLS.) and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:23
-	19	((216/24).CCLS.) and ("<100>" or "<111>" or "<110>") and {mirror adj array\$1}	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:23
-	117	((216/24).CCLS.) and ("<100>" or "<111>" or "<110>") and mirror\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:33
-	166	((216/24).CCLS.) and mirror\$1 and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:37
-	933	{mirror\$1 and etch\$3}.clm. and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:15
-	193	{mirror\$1 and array\$1 and etch\$3}.clm. and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:16
-	156	{mirror\$1 and etch\$3}.clm. and ("<100>" or "<111>" or "<110>").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:25
-	45	{mirror\$1 and etch\$3 and (mask\$3 or \$5resist\$1)}.clm. and ("<100>" or "<111>" or "<110>").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:26
-	471	((({mirror\$1 or micro\$1mirror\$1) and (array\$1 or micro\$1mechanical or micro\$1electro\$1mechanical or MEMS)).ti.) and (method\$1 or forming or making or fabricating).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:40
-	79	((({mirror\$1 or micro\$1mirror\$1) and (array\$1 or micro\$1mechanical or micro\$1electro\$1mechanical or MEMS)).ti.) and (method\$1 or forming or making or fabricating).ti.) and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:27
-	62	((({mirror\$1 or micro\$1mirror\$1) and (array\$1 or micro\$1mechanical or micro\$1electro\$1mechanical or MEMS)).ti.) and (method\$1 or forming or making or fabricating).ti.) and ("<100>" or "<111>" or "<110>") and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:32
-	13	((216/24).CCLS.) and ("<100>" or "<111>" or "<110>") and mirror\$1 and {alignment adj {feature\$1 or mark\$1}}	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:37

-	167	((216/24).CCLS.) and \$5mirror\$1 and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:18
-	3	((216/24).CCLS.) and mirror\$1 and (etch adj plane\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:39
-	91	((216/24).CCLS.) and mirror\$1 and plane\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:39
-	41	((216/24).CCLS.) and mirror\$1 and array\$1 and plane\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:42
-	1636	(((\$6mirror\$1) and (array\$1 or MEMS)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:01
-	46	(((\$6mirror\$1) and (array\$1 or MEMS)).ti. and plane\$1 and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:21
-	29	(((\$6mirror\$1) and (array\$1 or MEMS)).ti. and plane\$1 and mask\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:44
-	52	(((\$6mirror\$1) and (array\$1 or MEMS)).ti. and plane\$1 and etch\$3) or (((\$6mirror\$1) and (array\$1 or MEMS)).ti. and plane\$1 and mask\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 15:44
-	1	2002-405915.NRAN.	DERWENT	2003/11/07 15:53
-	658	(359/223).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:21
-	527	(359/224).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:21
-	167	(359/225).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:21
-	206	(359/226).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:22
-	1216	(257/431).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:24
-	1150	(257/432).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:24

-	805	(257/433).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:25
-	924	(257/435).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:25
-	819	(257/443).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:25
-	79	((((mirror\$1 or micro\$1mirror\$1) and (array\$1 or micro\$1mechanical or micro\$1electro\$1mechanical or MEMS)).ti.) and (method\$1 or forming or making or fabricating).ti.) and ("{100}" or "{111}" or "{110}"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:28
-	358	((216/24).CCLS.) and ("{100}" or "{111}" or "{110}"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:30
-	162	(\$6mirror\$1 and ("{100}" or "{111}" or "{110}")) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:23
-	30	(\$6mirror\$1 and (crystallographic) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:33
-	270	(\$6mirror\$1 and (plane\$1) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/07 16:34
-	9181	(((\$6mirror\$1 or optical) and (array\$1 or MEMS)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:03
-	1381	(((\$6mirror\$1 or optical) and (array\$1 or MEMS)).ti.) and plane\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:02
-	217	(((\$6mirror\$1 or optical) and (array\$1 or MEMS)).ti.) and plane\$1 and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:03
-	6196	(optical adj switch).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:04
-	164	(optical adj switch).ti. and plane\$1 and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:04
-	370	(((((\$6mirror\$1 or optical) and (array\$1 or MEMS)).ti.) and plane\$1 and etch\$3) or ((optical adj switch).ti. and plane\$1 and etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:04

-	3	((("5828485") or ("5953151")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:29
-	112	(torsion adj beam) and (address adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 17:23
-	5683	spatial adj light adj modulator\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:37
-	311	(spatial adj light adj modulator\$1).ti. and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:39
-	14	(spatial adj light adj modulator\$1).ti. and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:40
-	65	(MEMS or micromechanical).ti. and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:41
-	201	(\$6mirror\$1).ti. and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:46
-	48	(spatial adj light adj modulator\$1).ti. and (torsion adj (beam or hinge))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 16:48
-	101	(torsion adj hinge) and (address adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 17:23
-	155	((torsion adj hinge) and (address adj electrode)) or ((torsion adj beam) and (address adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 17:27
-	746	(\$6mirror\$1 and (beam or hinge) and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:24
-	171	(micromirror\$1 or micro-mirror\$1).ti. and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 17:30
-	675	(micromirror\$1 or micro-mirror\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/10 17:38
-	71	(\$6mirror\$1 and (beam or hinge) and mask\$3 and ("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}").clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:28

-	467	(\$6mirror\$1 and (beam or hinge) and mask\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:29
-	27	(\$6mirror\$1 and (beam or hinge) and mask\$3 and plane\$1 and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:30
-	90	(\$6mirror\$1 and (beam or hinge) and mask\$3 and plane\$1 and (MEMS or array\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:30
-	1351	(spatial adj light adj modulator\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:34
-	10	(spatial adj light adj modulator\$1) and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:13
-	14	(light adj modulator\$1) and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:36
-	7	(spatial adj light adj modulator\$1).ti. and (etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:38
-	0	(MEMS.).ti. and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:40
-	12	(MEMS or \$6mirror\$1).ti. and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:42
-	11	(micromechanical or microstructure\$1).ti. and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 13:42
-	155	(438/24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 14:55
-	269	(438/34).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 15:13
-	516	(438/40).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:00
-	170	(438/66).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 14:57

-	200	(438/69).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 14:57
-	237	(438/72).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 14:58
-	381	(438/401).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 14:58
-	778	(438/400).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:01
-	113	(438/405).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:01
-	364	(438/734).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:11
-	9	((438/734).CCLS.) and plane\$1.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:12
-	7	((438/400).CCLS.) and plane\$1.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:12
-	38	(spatial adj light adj modulator\$1) and (mask\$3 and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 17:44
-	798	(light adj valve).clm. and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:16
-	205	(\$6mirror\$1 and array\$1 and etch\$3).clm. and ("<100>" or "<111>" or "<110>")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:20
-	177	(\$6mirror\$1 and torsion).clm. and (plane\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 16:21
-	134	(micromirror\$1 and (KOH or (potassium adj hydroxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 17:58
-	2	compensation adj rectangle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/12 17:46

-	12	(micromirror\$1 same (bulk adj micromachining))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/12 18:00
-	52	(mirror\$1 same (bulk adj micromachining))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/12 18:00